S-8200A Series

BATTERY PROTECTION IC FOR 1-CELL PACK

www.sii-ic.com

Rev.3.4_00

The S-8200A Series is a protection IC for 1-cell lithium-ion / lithium polymer rechargeable batteries and includes high-accuracy voltage detectors and delay circuits.
The S-8200A Series is suitable for protecting single-cell rechargeable lithium-ion / lithium polymer battery packs from overcharge, overdischarge, and overcurrent.

■ Features

- High-accuracy voltage detection circuit

Overcharge detection voltage	3.5 V to 4.5 V (5 mV steps)	Accuracy ±20 mV (Ta = +25°C)
		Accuracy ±25 mV (Ta = −10°C to +60°C)
Overcharge release voltage	3.1 V to 4.5 V*1	Accuracy ±30 mV
Overdischarge detection voltage	2.0 V to 3.4 V (10 mV steps)	Accuracy ±35 mV
Overdischarge release voltage	2.0 V to 3.4 V*2	Accuracy ±50 mV
Discharge overcurrent detection voltage	0.05 V to 0.20 V (10 mV steps)	Accuracy ±10 mV
Load short-circuiting detection voltage	0.5 V (fixed)	Accuracy ±100 mV
Charge overcurrent detection voltage	−0.20 V to −0.05 V (25 mV steps)	Accuracy ±15 mV

- Detection delay times are generated only by an internal circuit (external capacitors are unnecessary).
  Accuracy ±20%
- High-withstanding-voltage device is used for charger connection pins
  (VM pin and CO pin: Absolute maximum rating = 28 V)
- 0 V battery charge function "available" / "unavailable" is selectable.
- Power-down function "available" / "unavailable" is selectable.
- Wide operation temperature range Ta = −40°C to +85°C
- Low current consumption
  During operation 2.8 µA typ., 5.0 µA max. (Ta = +25°C)
  During power-down 0.1 µA max. (Ta = +25°C)
- Lead-free (Sn 100%), halogen-free*3

***1.** Overcharge release voltage = Overcharge detection voltage − Overcharge hysteresis voltage
(Overcharge hysteresis voltage can be selected as 0 V or from a range of 0.1 V to 0.4 V in 50 mV steps.)
***2.** Overdischarge release voltage = Overdischarge detection voltage + Overdischarge hysteresis voltage
(Overdischarge hysteresis voltage can be selected as 0 V or from a range of 0.1 V to 0.7 V in 100 mV steps.)
***3.** Refer to "■ **Product Name Structure**" for details.

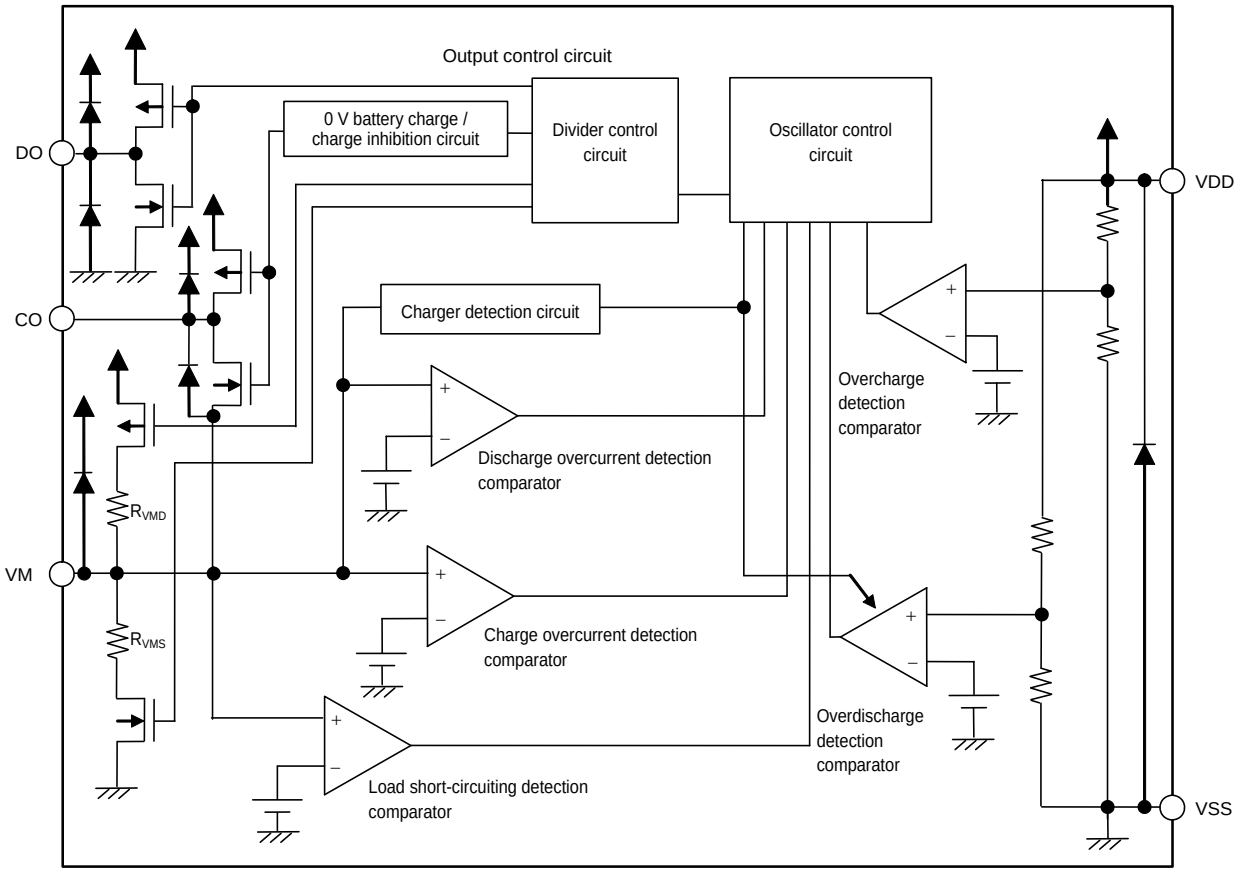
■ Applications

- Lithium-ion rechargeable battery pack
- Lithium polymer rechargeable battery pack

■ Packages

- SOT-23-6
- SNT-6A

■ Block Diagram

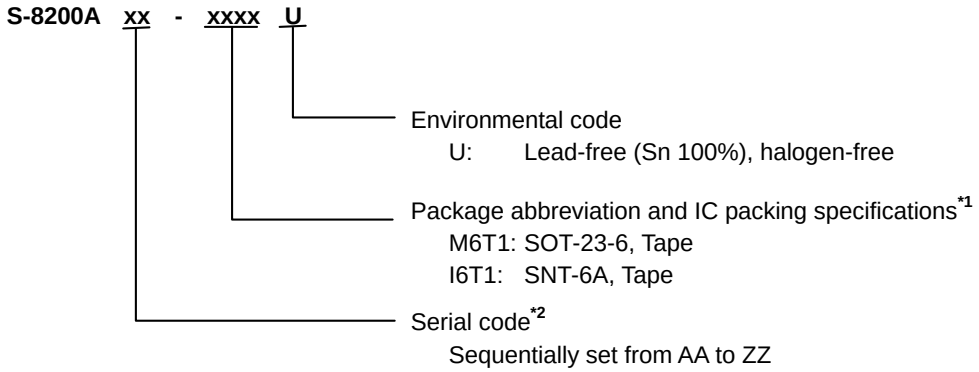


Remark All diodes shown in figure are parasitic diodes.

Figure 1

■ Product Name Structure

1. Product name



***1.** Refer to the tape drawing.
***2.** Refer to "**3. Product name list**".

2. Packages

Table 1 Package Drawing Codes

Package Name	Dimension	Tape	Reel	Land
SOT-23-6	MP006-A-P-SD	MP006-A-C-SD	MP006-A-R-SD	–
SNT-6A	PG006-A-P-SD	PG006-A-C-SD	PG006-A-R-SD	PG006-A-L-SD

3. Product name list

3. 1 SOT-23-6

Table 2

Product Name	Overcharge Detection Voltage [V_{CU}]	Overcharge Release Voltage [V_{CL}]	Over-discharge Detection Voltage [V_{DL}]	Over-discharge Release Voltage [V_{DU}]	Discharge Overcurrent Detection Voltage [V_{DIOV}]	Charge Overcurrent Detection Voltage [V_{CIOV}]	0 V Battery Charge Function	Delay Time Combination*1	Power-down Function
S-8200AAC-M6T1U	4.225 V	4.025 V	2.500 V	2.900 V	0.150 V	−0.150 V	Available	(1)	Unavailable
S-8200AAH-M6T1U	4.375V	4.175 V	2.300 V	2.300 V	0.130 V	−0.100 V	Available	(2)	Available
S-8200AAY-M6T1U	4.150 V	4.050 V	2.500 V	2.800 V	0.160 V	−0.100 V	Available	(1)	Unavailable
S-8200ABE-M6T1U	4.200 V	4.000 V	3.200 V	3.400 V	0.150 V	−0.100 V	Unavailable	(2)	Available

***1.** Refer to **Table 3** about the details of the delay time combinations.

3. 2 SNT-6A

Table 3

Product Name	Overcharge Detection Voltage [V_{CU}]	Overcharge Release Voltage [V_{CL}]	Over-discharge Detection Voltage [V_{DL}]	Over-discharge Release Voltage [V_{DU}]	Discharge Overcurrent Detection Voltage [V_{DIOV}]	Charge Overcurrent Detection Voltage [V_{CIOV}]	0 V Battery Charge Function	Delay Time Combination*1	Power-down Function
S-8200AAA-I6T1U	4.225 V	4.025 V	2.500 V	2.900 V	0.150 V	−0.150 V	Unavailable	(1)	Available
S-8200AAB-I6T1U	4.250 V	4.050 V	2.400 V	2.900 V	0.050 V	−0.100 V	Unavailable	(1)	Available
S-8200AAC-I6T1U	4.225 V	4.025 V	2.500 V	2.900 V	0.150 V	−0.150 V	Available	(1)	Unavailable
S-8200AAD-I6T1U	4.275 V	4.075 V	2.600 V	2.600 V	0.120 V	−0.100 V	Available	(2)	Available
S-8200AAF-I6T1U	4.225 V	4.025 V	2.800 V	2.800 V	0.150 V	−0.150 V	Unavailable	(1)	Available
S-8200AAG-I6T1U	4.275 V	4.075 V	2.600 V	2.600 V	0.180 V	−0.125 V	Available	(2)	Available
S-8200AAH-I6T1U	4.375 V	4.175 V	2.300 V	2.300 V	0.130 V	−0.100 V	Available	(2)	Available
S-8200ABA-I6T1U	4.425 V	4.225 V	2.300 V	2.300 V	0.165 V	−0.100 V	Unavailable	(2)	Available

***1.** Refer to **Table 4** about the details of the delay time combinations.

Remark Please contact our sales office for the products with detection voltage value other than those specified above.

Table 4

Delay Time Combination	Overcharge Detection Delay Time [t_{CU}]	Overdischarge Detection Delay Time [t_{DL}]	Discharge Overcurrent Detection Delay Time [t_{DIOV}]	Load Short-circuiting Detection Delay Time [t_{SHORT}]	Charge Overcurrent Detection Delay Time [t_{CIOV}]
(1)	1.0 s	64 ms	8 ms	250 μs	8 ms
(2)	1.0 s	32 ms	8 ms	250 μs	8 ms

Remark The delay times can be changed within the range listed **Table 5**. For details, please contact our sales office.

Table 5

Delay Time	Symbol	Selection Range			Remark
Overcharge detection delay time	t_{CU}	256 ms	512 ms	1.0 s*1	Select a value from the left.
Overdischarge detection delay time	t_{DL}	32 ms	64 ms*1	128 ms	Select a value from the left.
Discharge overcurrent detection delay time	t_{DIOV}	4 ms	8 ms*1	16 ms	Select a value from the left.
Load short-circuiting detection delay Time	t_{SHORT}	250 μs*1	500 μs	1 ms	Select a value from the left.
Charge overcurrent detection delay time	t_{CIOV}	4 ms	8 ms*1	16 ms	Select a value from the left.

***1.** This value is the delay time of the standard product.

■ Pin Configurations

1. SOT-23-6

Top view

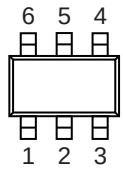


Figure 2

Table 6

Pin No.	Symbol	Description
1	DO	Connection pin of discharge control FET gate (CMOS output)
2	VM	Voltage detection pin between VM pin and VSS pin (Overcurrent / charger detection pin)
3	CO	Connection pin of charge control FET gate (CMOS output)
4	NC*1	No connection
5	VDD	Connection pin for positive power supply input
6	VSS	Connection pin for negative power supply input

***1.** The NC pin is electrically open.
The NC pin can be connected to VDD pin or VSS pin.

2. SNT-6A

Top view

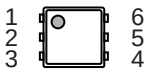


Figure 3

Table 7

Pin No.	Symbol	Description
1	NC*1	No connection
2	CO	Connection pin of charge control FET gate (CMOS output)
3	DO	Connection pin of discharge control FET gate (CMOS output)
4	VSS	Connection pin for negative power supply input
5	VDD	Connection pin for positive power supply input
6	VM	Voltage detection pin between VM pin and VSS pin (Overcurrent / charger detection pin)

***1.** The NC pin is electrically open.
The NC pin can be connected to VDD pin or VSS pin.

■ Absolute Maximum Ratings

Table 8

(Ta = +25°C unless otherwise specified)

Item		Symbol	Applied Pin	Absolute Maximum Rating	Unit
Input voltage between VDD pin and VSS pin		V_{DS}	VDD	V_{SS} − 0.3 to V_{SS} + 12	V
VM pin input voltage		V_{VM}	VM	V_{DD} − 28 to V_{DD} + 0.3	V
DO pin output voltage		V_{DO}	DO	V_{SS} − 0.3 to V_{DD} + 0.3	V
CO pin output voltage		V_{CO}	CO	V_{VM} − 0.3 to V_{DD} + 0.3	V
Power dissipation	SOT-23-6	P_D	−	650[*1]	mW
	SNT-6A		−	400[*1]	mW
Operation ambient temperature		T_{opr}	−	−40 to +85	°C
Storage temperature		T_{stg}	−	−55 to +125	°C

***1.** When mounted on board
[Mounted board]
(1) Board size: 114.3 mm × 76.2 mm × t1.6 mm
(2) Board name: JEDEC STANDARD51-7

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

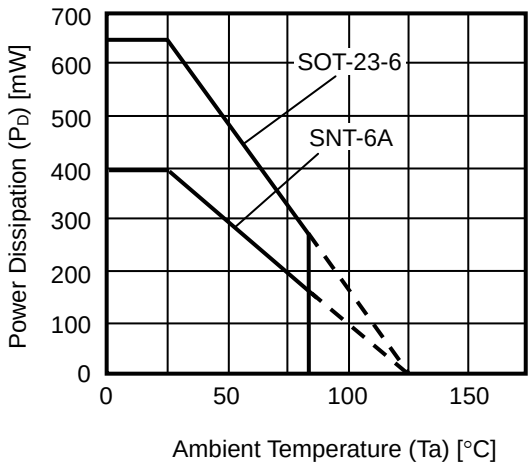


Figure 4 Power Dissipation of Package (When Mounted on Board)

■ Electrical Characteristics

1. Ta = +25°C

Table 9

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
DETECTION VOLTAGE							
Overcharge detection voltage	V_{CU}	–	V_{CU} – 0.020	V_{CU}	V_{CU} + 0.020	V	1
		Ta = –10°C to +60°C*1	V_{CU} – 0.025	V_{CU}	V_{CU} + 0.025	V	1
Overcharge release voltage	V_{CL}	$V_{CL} \neq V_{CU}$	V_{CL} – 0.030	V_{CL}	V_{CL} + 0.030	V	1
		$V_{CL} = V_{CU}$	V_{CL} – 0.025	V_{CL}	V_{CL} + 0.020	V	1
Overdischarge detection voltage	V_{DL}	–	V_{DL} – 0.035	V_{DL}	V_{DL} + 0.035	V	2
Overdischarge release voltage	V_{DU}	$V_{DL} \neq V_{DU}$	V_{DU} – 0.050	V_{DU}	V_{DU} + 0.050	V	2
		$V_{DL} = V_{DU}$	V_{DU} – 0.035	V_{DU}	V_{DU} + 0.035	V	2
Discharge overcurrent detection voltage	V_{DIOV}	–	V_{DIOV} – 0.010	V_{DIOV}	V_{DIOV} + 0.010	V	2
Load short-circuiting detection voltage	V_{SHORT}	–	0.40	0.50	0.60	V	2
Charge overcurrent detection voltage	V_{CIOV}	–	V_{CIOV} – 0.015	V_{CIOV}	V_{CIOV} + 0.015	V	2
0 V BATTERY CHARGE FUNCTION							
0 V battery charge starting charger voltage	V_{0CHA}	0 V battery charge function "available"	0.0	0.7	1.0	V	2
0 V battery charge inhibition battery voltage	V_{0INH}	0 V battery charge function "unavailable"	0.6	0.8	1.1	V	2
INTERNAL RESISTANCE							
Resistance between VM pin and VDD pin	R_{VMD}	V_{DD} = 1.8 V, V_{VM} = 0 V	100	300	900	kΩ	3
Resistance between VM pin and VSS pin	R_{VMS}	V_{DD} = 3.4 V, V_{VM} = 1.0 V	10	20	40	kΩ	3
INPUT VOLTAGE							
Operating voltage between VDD pin and VSS pin	V_{DSOP1}	–	1.5	–	6.5	V	–
Operating voltage between VDD pin and VM pin	V_{DSOP2}	–	1.5	–	28	V	–
INPUT CURRENT (WITH POWER-DOWN FUNCTION)							
Current consumption during operation	I_{OPE}	V_{DD} = 3.4 V, V_{VM} = 0 V	1.0	2.8	5.0	μA	2
Current consumption during power-down	I_{PDN}	V_{DD} = V_{VM} = 1.5 V	–	–	0.1	μA	2
INPUT CURRENT (WITHOUT POWER-DOWN FUNCTION)							
Current consumption during operation	I_{OPE}	V_{DD} = 3.4 V, V_{VM} = 0 V	1.0	2.8	5.0	μA	2
Current consumption during overdischarge	I_{OPED}	V_{DD} = V_{VM} = 1.5 V	–	–	3.5	μA	2
OUTPUT RESISTANCE							
CO pin resistance "H"	R_{COH}	V_{CO} = 3.0 V, V_{DD} = 3.4 V, V_{VM} = 0 V	5	10	20	kΩ	4
CO pin resistance "L"	R_{COL}	V_{CO} = 0.4 V, V_{DD} = 4.6 V, V_{VM} = 0 V	5	10	20	kΩ	4
DO pin resistance "H"	R_{DOH}	V_{DO} = 3.0 V, V_{DD} = 3.4 V, V_{VM} = 0 V	5	10	20	kΩ	4
DO pin resistance "L"	R_{DOL}	V_{DO} = 0.4 V, V_{DD} = 1.8 V, V_{VM} = 0 V	5	10	20	kΩ	4
DELAY TIME							
Overcharge detection delay time	t_{CU}	–	t_{CU} × 0.8	t_{CU}	t_{CU} × 1.2	–	5
Overdischarge detection delay time	t_{DL}	–	t_{DL} × 0.8	t_{DL}	t_{DL} × 1.2	–	5
Discharge overcurrent detection delay time	t_{DIOV}	–	t_{DIOV} × 0.8	t_{DIOV}	t_{DIOV} × 1.2	–	5
Load short-circuiting detection delay time	t_{SHORT}	–	t_{SHORT} × 0.8	t_{SHORT}	t_{SHORT} × 1.2	–	5
Charge overcurrent detection delay time	t_{CIOV}	–	t_{CIOV} × 0.8	t_{CIOV}	t_{CIOV} × 1.2	–	5

***1.** Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.

2. Ta = –40°C to +85°C[*1]

Table 10

(Ta = –40°C to +85°C[*1] unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
DETECTION VOLTAGE							
Overcharge detection voltage	V_{CU}	–	V_{CU} – 0.045	V_{CU}	V_{CU} + 0.030	V	1
Overcharge release voltage	V_{CL}	$V_{CL} \neq V_{CU}$	V_{CL} – 0.070	V_{CL}	V_{CL} + 0.040	V	1
		$V_{CL} = V_{CU}$	V_{CL} – 0.050	V_{CL}	V_{CL} + 0.030	V	1
Overdischarge detection voltage	V_{DL}	–	V_{DL} – 0.070	V_{DL}	V_{DL} + 0.045	V	2
Overdischarge release voltage	V_{DU}	$V_{DL} \neq V_{DU}$	V_{DU} – 0.090	V_{DU}	V_{DU} + 0.060	V	2
		$V_{DL} = V_{DU}$	V_{DU} – 0.070	V_{DU}	V_{DU} + 0.045	V	2
Discharge overcurrent detection voltage	V_{DIOV}	–	V_{DIOV} – 0.010	V_{DIOV}	V_{DIOV} + 0.010	V	2
Load short-circuiting detection voltage	V_{SHORT}	–	0.40	0.50	0.60	V	2
Charge overcurrent detection voltage	V_{CIOV}	–	V_{CIOV} – 0.015	V_{CIOV}	V_{CIOV} + 0.015	V	2
0 V BATTERY CHARGE FUNCTION							
0 V battery charge starting charger voltage	V_{0CHA}	0 V battery charge function "available"	0.0	0.7	1.5	V	2
0 V battery charge inhibition battery voltage	V_{0INH}	0 V battery charge function "unavailable"	0.4	0.8	1.3	V	2
INTERNAL RESISTANCE							
Resistance between VM pin and VDD pin	R_{VMD}	V_{DD} = 1.8 V, V_{VM} = 0 V	78	300	1310	kΩ	3
Resistance between VM pin and VSS pin	R_{VMS}	V_{DD} = 3.4 V, V_{VM} = 1.0 V	7.2	20	44	kΩ	3
INPUT VOLTAGE							
Operating voltage between VDD pin and VSS pin	V_{DSOP1}	–	1.5	–	6.5	V	–
Operating voltage between VDD pin and VM pin	V_{DSOP2}	–	1.5	–	28	V	–
INPUT CURRENT (WITH POWER-DOWN FUNCTION)							
Current consumption during operation	I_{OPE}	V_{DD} = 3.4 V, V_{VM} = 0 V	0.7	2.8	5.5	μA	2
Current consumption during power-down	I_{PDN}	V_{DD} = V_{VM} = 1.5 V	–	–	0.15	μA	2
INPUT CURRENT (WITHOUT POWER-DOWN FUNCTION)							
Current consumption during operation	I_{OPE}	V_{DD} = 3.4 V, V_{VM} = 0 V	0.7	2.8	5.5	μA	2
Current consumption during overdischarge	I_{OPED}	V_{DD} = V_{VM} = 1.5 V	–	–	3.8	μA	2
OUTPUT RESISTANCE							
CO pin resistance "H"	R_{COH}	V_{CO} = 3.0 V, V_{DD} = 3.4 V, V_{VM} = 0 V	2.4	10	30	kΩ	4
CO pin resistance "L"	R_{COL}	V_{CO} = 0.4 V, V_{DD} = 4.6 V, V_{VM} = 0 V	2.4	10	30	kΩ	4
DO pin resistance "H"	R_{DOH}	V_{DO} = 3.0 V, V_{DD} = 3.4 V, V_{VM} = 0 V	2.4	10	30	kΩ	4
DO pin resistance "L"	R_{DOL}	V_{DO} = 0.4 V, V_{DD} = 1.8 V, V_{VM} = 0 V	2.4	10	30	kΩ	4
DELAY TIME							
Overcharge detection delay time	t_{CU}	–	t_{CU} × 0.6	t_{CU}	t_{CU} × 1.6	–	5
Overdischarge detection delay time	t_{DL}	–	t_{DL} × 0.6	t_{DL}	t_{DL} × 1.6	–	5
Discharge overcurrent detection delay time	t_{DIOV}	–	t_{DIOV} × 0.6	t_{DIOV}	t_{DIOV} × 1.6	–	5
Load short-circuiting detection delay time	t_{SHORT}	–	t_{SHORT} × 0.6	t_{SHORT}	t_{SHORT} × 1.6	–	5
Charge overcurrent detection delay time	t_{CIOV}	–	t_{CIOV} × 0.6	t_{CIOV}	t_{CIOV} × 1.6	–	5

***1.** Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.

■ Test Circuits

Caution Unless otherwise specified, the output voltage levels "H" and "L" at CO pin (V_{CO}) and DO pin (V_{DO}) are judged by the threshold voltage (1.0 V) of the N-channel FET. Judge the CO pin level with respect to V_{VM} and the DO pin level with respect to V_{SS}.

1. Overcharge detection voltage, overcharge release voltage (Test circuit 1)

Overcharge detection voltage (V_{CU}) is defined as the voltage V1 at which V_{CO} goes from "H" to "L" when the voltage V1 is gradually increased from the starting condition of V1 = 3.4 V. Overcharge release voltage (V_{CL}) is defined as the voltage V1 at which V_{CO} goes from "L" to "H" when the voltage V1 is then gradually decreased. Overcharge hysteresis voltage (V_{HC}) is defined as the difference between V_{CU} and V_{CL}.

2. Overdischarge detection voltage, overdischarge release voltage (Test circuit 2)

Overdischarge detection voltage (V_{DL}) is defined as the voltage V1 at which V_{DO} goes from "H" to "L" when the voltage V1 is gradually decreased from the starting condition of V1 = 3.4 V, V2 = 0 V. Overdischarge release voltage (V_{DU}) is defined as the voltage V1 at which V_{DO} goes from "L" to "H" when the voltage V1 is then gradually increased. Overdischarge hysteresis voltage (V_{HD}) is defined as the difference between V_{DU} and V_{DL}.

3. Discharge overcurrent detection voltage (Test circuit 2)

Discharge overcurrent detection voltage (V_{DIOV}) is defined as the voltage V2 whose delay time for changing V_{DO} from "H" to "L" is discharge overcurrent delay time (t_{DIOV}) when the voltage V2 is increased from the starting condition of V1 = 3.4 V, V2 = 0 V.

4. Load short-circuiting detection voltage (Test circuit 2)

Load short-circuiting detection voltage (V_{SHORT}) is defined as the voltage V2 whose delay time for changing V_{DO} from "H" to "L" is load short-circuiting delay time (t_{SHORT}) when the voltage V2 is increased from the starting condition of V1 = 3.4 V, V2 = 0 V.

5. Charge overcurrent detection voltage (Test circuit 2)

Charge overcurrent detection voltage (V_{CIOV}) is defined as the voltage V2 whose delay time for changing V_{CO} from "H" to "L" is charge overcurrent delay time (t_{CIOV}) when the voltage V2 is decreased from the starting condition of V1 = 3.4 V, V2 = 0 V.

6. Current consumption during operation (Test circuit 2)

The current consumption during operation (I_{OPE}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = 3.4 V and V2 = 0 V.

7. Current consumption during power-down, current consumption during overdischarge (Test circuit 2)

7. 1 With power-down function

The current consumption during power-down (I_{PDN}) is I_{DD} under the set conditions of V1 = V2 = 1.5 V.

7. 2 Without power-down function

The current consumption during overdischarge (I_{OPED}) is I_{DD} under the set conditions of V1 = V2 = 1.5 V.

8. Resistance between VM pin and VDD pin (Test circuit 3)

R_{VMD} is the resistance between VM pin and VDD pin under the set conditions of V1 = 1.8 V, V2 = 0 V.

9. Resistance between VM pin and VSS pin (Test circuit 3)

R_{VMS} is the resistance between VM pin and VSS pin under the set conditions of V1 = 3.4 V, V2 = 1.0 V.

10. CO pin resistance "H" (Test circuit 4)

The CO pin resistance "H" (R_{COH}) is the resistance between VDD pin and CO pin under the set conditions of V1 = 3.4 V, V2 = 0 V, V3 = 3.0 V.

11. CO pin resistance "L" (Test circuit 4)

The CO pin resistance "L" (R_{COL}) is the resistance between VM pin and CO pin under the set conditions of V1 = 4.6 V, V2 = 0 V, V3 = 0.4 V.

12. DO pin resistance "H" (Test circuit 4)

The DO pin H resistance (R_{DOH}) is the resistance between VDD pin and DO pin under the set conditions of V1 = 3.4 V, V2 = 0 V, V4 = 3.0 V.

13. DO pin resistance "L" (Test circuit 4)

The DO pin L resistance (R_{DOL}) is the resistance between VSS pin and DO pin under the set conditions of V1 = 1.8 V, V2 = 0 V, V4 = 0.4 V.

14. Overcharge detection delay time (Test circuit 5)

The overcharge detection delay time (t_{CU}) is the time needed for V_{CO} to go to "L" just after the voltage V1 increases and exceeds V_{CU} under the set conditions of V1 = 3.4 V, V2 = 0 V.

15. Overdischarge detection delay time (Test circuit 5)

The overdischarge detection delay time (t_{DL}) is the time needed for V_{DO} to go to "L" after the voltage V1 decreases and falls below V_{DL} under the set conditions of V1 = 3.4 V, V2 = 0 V.

16. Discharge overcurrent detection delay time (Test circuit 5)

The discharge overcurrent detection delay time (t_{DIOV}) is the time needed for V_{DO} to go to "L" after the voltage V2 increases and exceeds V_{DIOV} under the set conditions of V1 = 3.4 V, V2 = 0 V.

17. Load short-circuiting detection delay time (Test circuit 5)

The load short-circuiting detection delay time (t_{SHORT}) is the time needed for V_{DO} to go to "L" after the voltage V2 increases and exceeds V_{SHORT} under the set conditions of V1 = 3.4 V, V2 = 0 V.

18. Charge overcurrent detection delay time (Test circuit 5)

The charge overcurrent detection delay time (t_{CIOV}) is the time needed for V_{CO} to go to "L" after the voltage V2 decreases and falls below V_{CIOV} under the set conditions of V1 = 3.4 V, V2 = 0 V.

19. 0 V battery charge starting charger voltage (0 V battery charge function "available") (Test circuit 2)

The 0 V charge starting charger voltage (V_{0CHA}) is defined as the absolute value of voltage V2 at which V_{CO} goes to "H" ($V_{CO} = V_{DD}$) when the voltage V2 is gradually decreased from the starting conditions of V1 = V2 = 0 V.

20. 0 V battery charge inhibition battery voltage (0 V battery charge function "unavailable") (Test circuit 2)

The 0 V charge inhibition battery voltage (V_{0INH}) is defined as the voltage V1 at which V_{CO} goes to "H" ($V_{CO} = V_{DD}$) when the voltage V1 is gradually increased, after setting V1 = 0 V, V2 = −4.0 V.

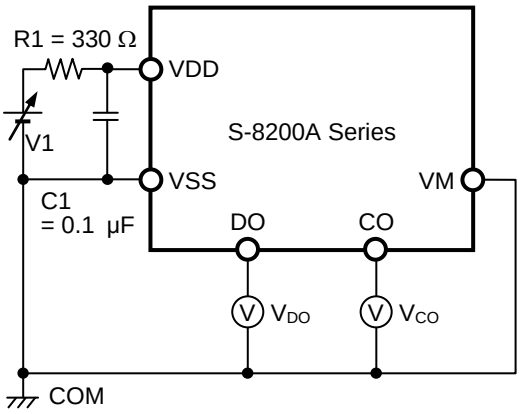


Figure 5 Test Circuit 1

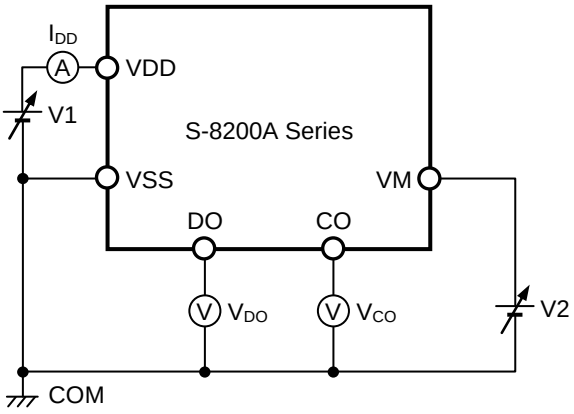


Figure 6 Test Circuit 2

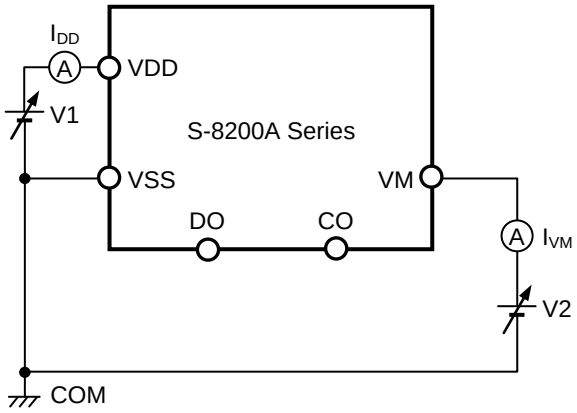


Figure 7 Test Circuit 3

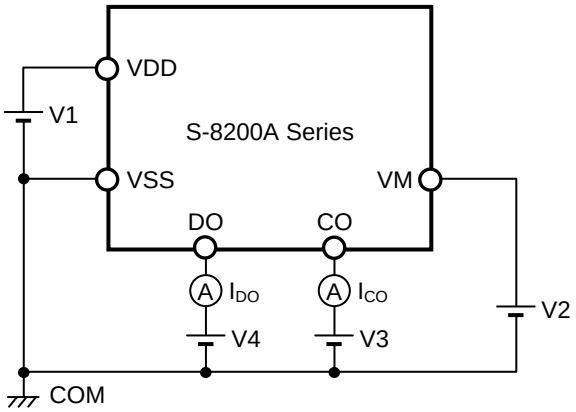


Figure 8 Test Circuit 4

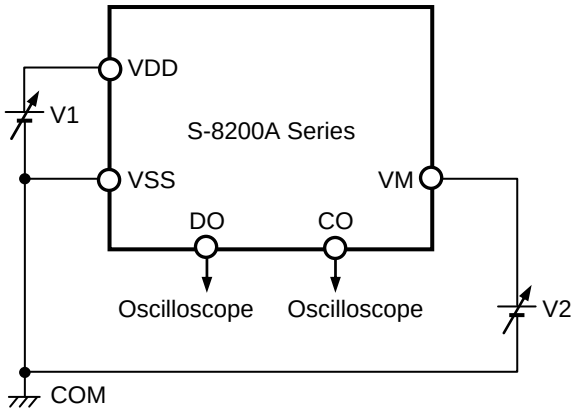


Figure 9 Test Circuit 5

■ Operation

Remark Refer to "■ **Battery Protection IC Connection Example**".

1. Normal status

The S-8200A Series monitors the voltage of the battery connected between the VDD pin and VSS pin and the voltage difference between the VM pin and VSS pin to control charging and discharging. When the battery voltage is in the range from overdischarge detection voltage (V_{DL}) to overcharge detection voltage (V_{CU}), and the VM pin voltage is in the range from charge overcurrent detection voltage (V_{CIOV}) to discharge overcurrent detection voltage (V_{DIOV}), the S-8200A Series turns both the charging and discharging control FETs on. This condition is called the normal status, and in this condition charging and discharging can be carried out freely.
The resistance (R_{VMD}) between the VM pin and VDD pin, and the resistance (R_{VMS}) between the VM pin and VSS pin are not connected in the normal status.

Caution When the battery is connected for the first time, discharging may not be enabled. In this case, short the VM pin and VSS pin, or set the VM pin's voltage at the level of V_{CIOV} or more and at the level of V_{DIOV} or less by connecting the charger. The S-8200A Series then returns to the normal status.

2. Overcharge status

When the battery voltage becomes higher than V_{CU} during charging in the normal status and detection continues for the overcharge detection delay time (t_{CU}) or longer, the S-8200A Series turns the charging control FET off to stop charging. This condition is called the overcharge status.
R_{VMD} and R_{VMS} are not connected in the overcharge status.
The overcharge status is released in the following two cases.

(1) In the case that the VM pin voltage is lower than V_{DIOV}, the S-8200A Series releases the overcharge status when the battery voltage falls below V_{CL}.
(2) In the case that the VM pin voltage is higher than or equal to V_{DIOV}, the S-8200A Series releases the overcharge status when the battery voltage falls below V_{CU}.

The discharge is started by connecting a load after the overcharge detection, the VM pin voltage rises more than the voltage at VSS pin due to the V_f voltage of the parasitic diode, because the discharge current flows through the parasitic diode in the charging control FET. If this VM pin voltage is higher than or equal to V_{DIOV}, the S-8200A Series releases the overcharge status when the battery voltage is lower than or equal to V_{CU}.

Caution If the battery is charged to a voltage higher than V_{CU} and the battery voltage does not fall below V_{CU} even when a heavy load is connected, discharge overcurrent detection and load short-circuiting detection do not function until the battery voltage falls below V_{CU}. Since an actual battery has an internal impedance of tens of mΩ, the battery voltage drops immediately after a heavy load that causes overcurrent is connected, and discharge overcurrent detection and load short-circuiting detection function.

3. Overdischarge status

When the battery voltage falls below overdischarge detection voltage (V_{DL}) during discharging in the normal status and the detection continues for the overdischarge detection delay time (t_{DL}) or longer, the S-8200A Series turns the discharging control FET off to stop discharging. This condition is called the overdischarge status.
Under the overdischarge status, the VM pin and VDD pin are shorted by R_{VMD} in the S-8200A Series. The VM pin voltage is pulled up by R_{VMD}.
When a battery in the overdischarge status is connected to a charger and provided that the VM pin voltage is lower than −0.7 V typ., the S-8200A Series releases the overdischarge status when the battery voltage reaches V_{DL} or higher.
When VM pin voltage is not lower than −0.7 V typ., the S-8200A Series releases the overdischarge status when the battery voltage reaches V_{DU} or higher.
R_{VMS} is not connected in the overdischarge status.

3. 1 With power-down function

Under the overdischarge status, when voltage difference between the VM pin and VDD pin is 0.8 V typ. or lower, the power-down function works and the current consumption is reduced to the current consumption during power-down (I_{PDN}). By connecting a battery charger, the power-down function is released when the VM pin voltage is 0.7 V typ. or lower.

4. Discharge overcurrent status (discharge overcurrent, load short-circuiting)

When a battery in the normal status is in the status where the voltage of the VM pin is equal to or higher than V_{DIOV} because the discharge current is higher than the specified value and the status lasts for the discharge overcurrent detection delay time (t_{DIOV}), the discharge control FET is turned off and discharging is stopped. This status is called the discharge overcurrent status.
In the discharge overcurrent status, the VM pin and VSS pin are shorted by the R_{VMS} in the S-8200A Series. However, the voltage of the VM pin is at the V_{DD} potential due to the load as long as the load is connected. When the load is disconnected, the VM pin returns to the V_{SS} potential.
The voltage at the VM pin returns to V_{DIOV} or lower, the S-8200A Series releases the discharge overcurrent status.
R_{VMD} is not connected in the discharge overcurrent detection status.

5. Charge overcurrent status

When a battery in the normal status is in the status where the voltage of the VM pin is lower than V_{CIOV} because the charge current is higher than the specified value and the status lasts for the charge overcurrent detection delay time (t_{CIOV}), the charge control FET is turned off and charging is stopped. This status is called the charge overcurrent status.
The S-8200A Series releases the charge overcurrent status when the voltage at the VM pin returns to V_{CIOV} or higher by removing the charger.
The charge overcurrent detection function does not work in the overdischarge status.
R_{VMD} and R_{VMS} are not connected in the charge overcurrent status.

6. 0 V battery charge function "available"

This function is used to recharge a connected battery whose voltage is 0 V due to self-discharge. When the 0 V battery charge starting charger voltage (V_{0CHA}) or a higher voltage is applied between the EB+ and EB− pins by connecting a charger, the charging control FET gate is fixed to the V_{DD} potential.
When the voltage between the gate and source of the charging control FET becomes equal to or higher than the threshold voltage due to the charger voltage, the charging control FET is turned on to start charging. At this time, the discharging control FET is off and the charging current flows through the internal parasitic diode in the discharging control FET. When the battery voltage becomes equal to or higher than V_{DU}, the S-8200A Series enters the normal status.

Caution
1. **Some battery providers do not recommend charging for a completely self-discharged battery. Please ask the battery provider to determine whether to enable or inhibit the 0 V battery charge function.**
2. **The 0 V battery charge function has higher priority than the charge overcurrent detection function. Consequently, a product in which use of the 0 V battery charge function is enabled charges a battery forcibly and the charge overcurrent cannot be detected when the battery voltage is lower than V_{DL}.**

7. 0 V battery charge function "unavailable"

This function inhibits recharging when a battery that is internally short-circuited (0 V battery) is connected. When the battery voltage is the 0 V battery charge inhibition battery voltage (V_{0INH}) or lower, the charging control FET gate is fixed to the EB− pin voltage to inhibit charging. When the battery voltage is V_{0INH} or higher, charging can be performed.

Caution **Some battery providers do not recommend charging for a completely self-discharged battery. Please ask the battery provider to determine whether to enable or inhibit the 0 V battery charge function.**

8. Delay circuit

The detection delay times are determined by dividing a clock of approximately 4 kHz by the counter.

Remark t_{DIOV} and t_{SHORT} start when V_{DIOV} is detected. When V_{SHORT} is detected over t_{SHORT} after V_{DIOV}, the S-8200A Series turns the discharging control FET off within t_{SHORT} from the time of detecting V_{SHORT}.

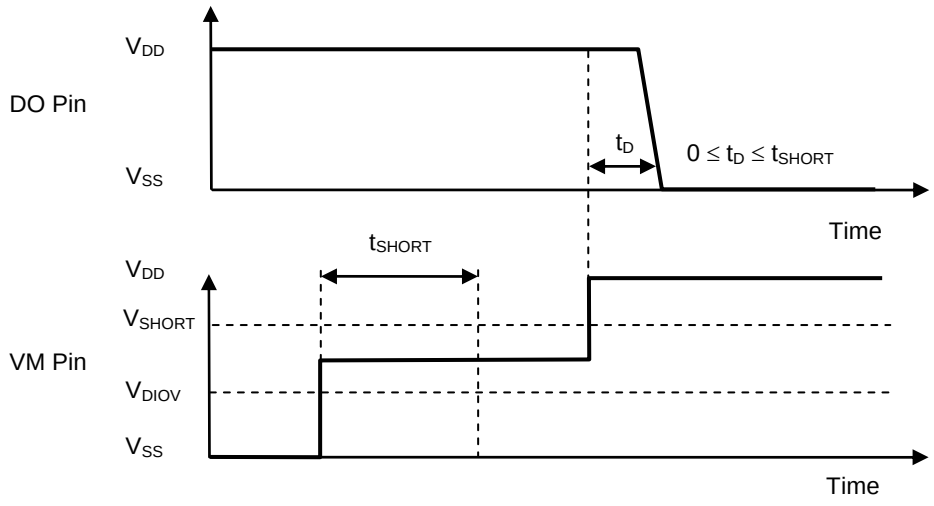
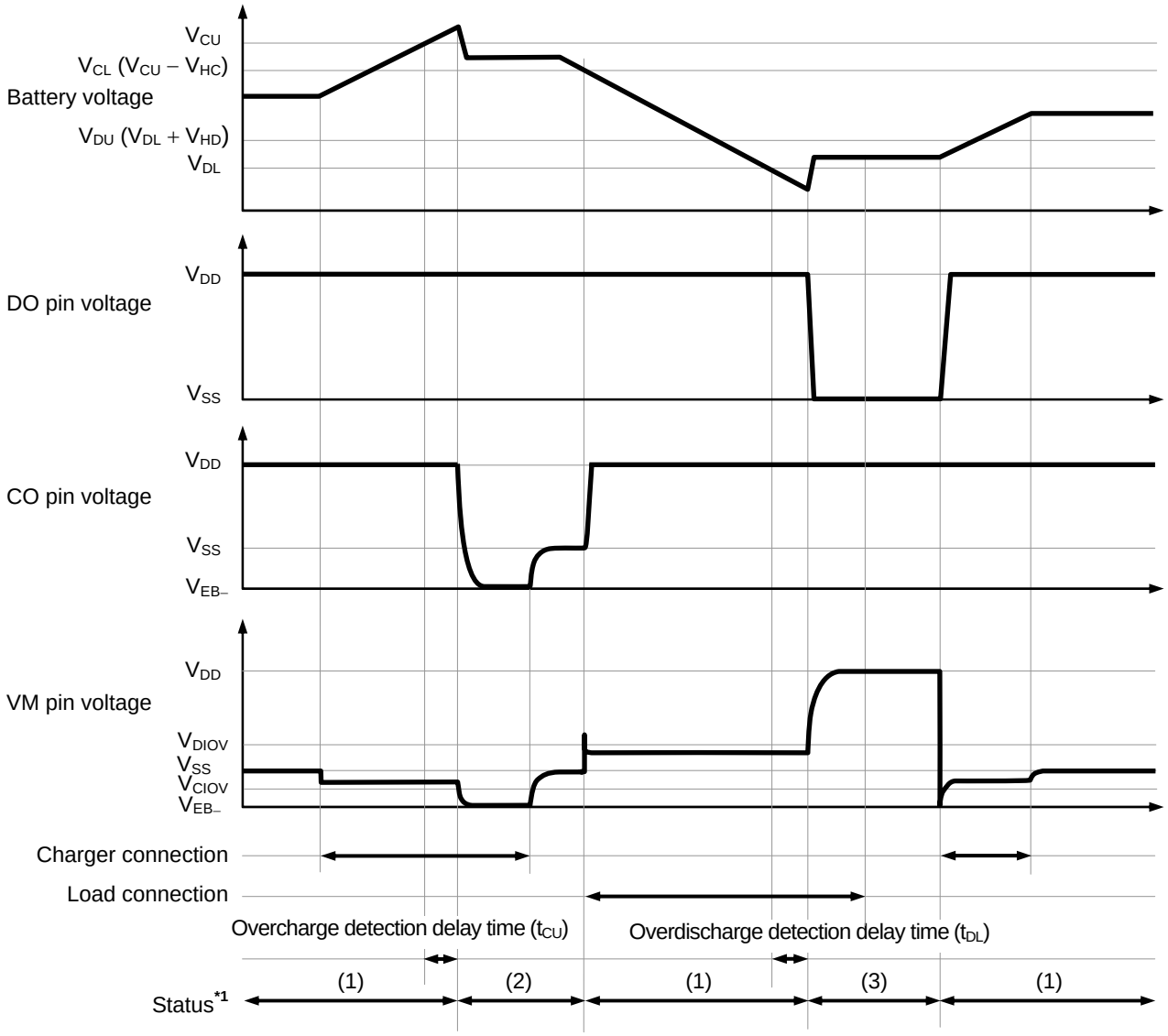


Figure 10

■ Timing Charts

1. Overcharge detection, overdischarge detection

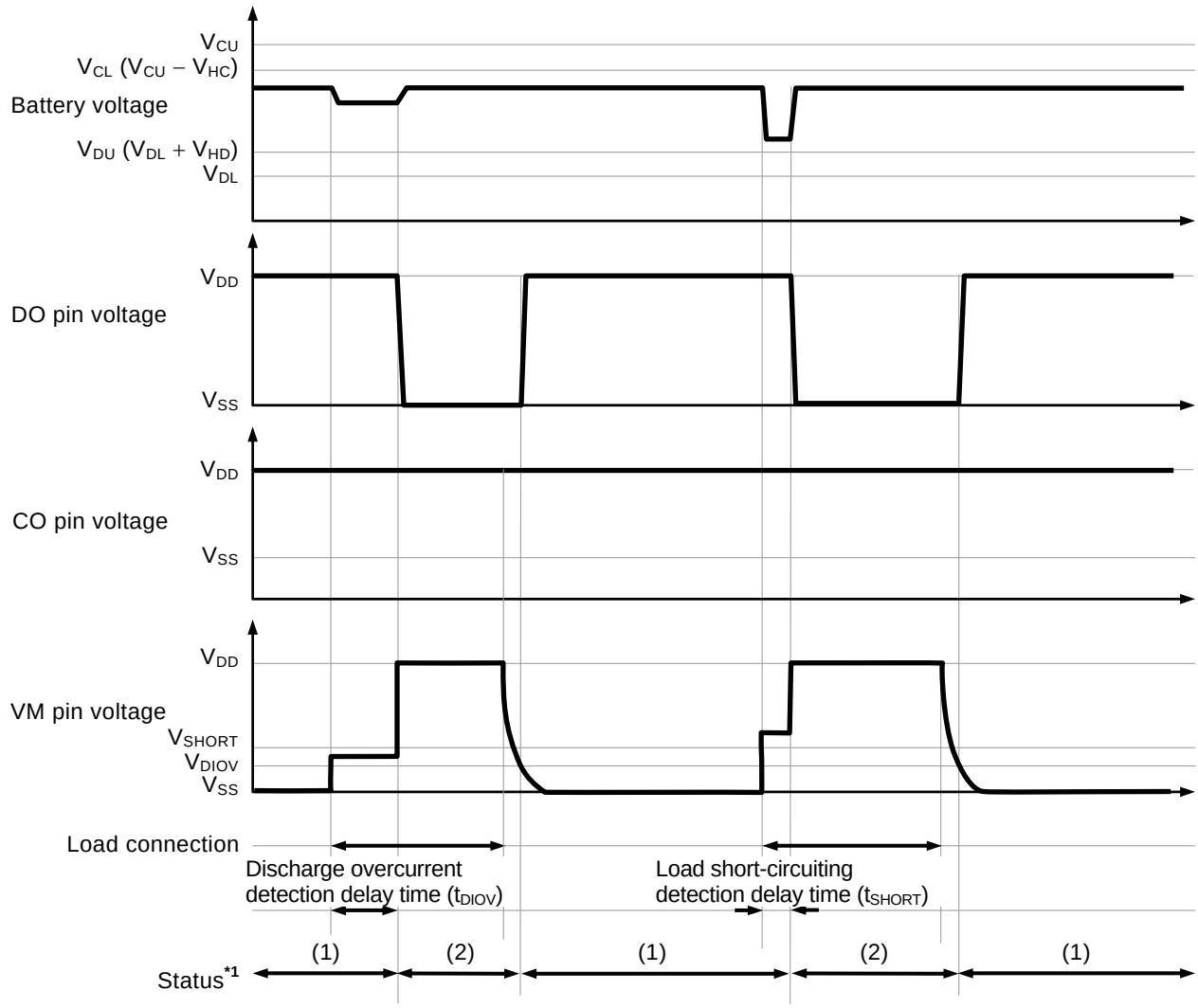


***1.** (1): Normal status
(2): Overcharge status
(3): Overdischarge status

Remark The charger is assumed to charge with a constant current.

Figure 11

2. Discharge overcurrent detection

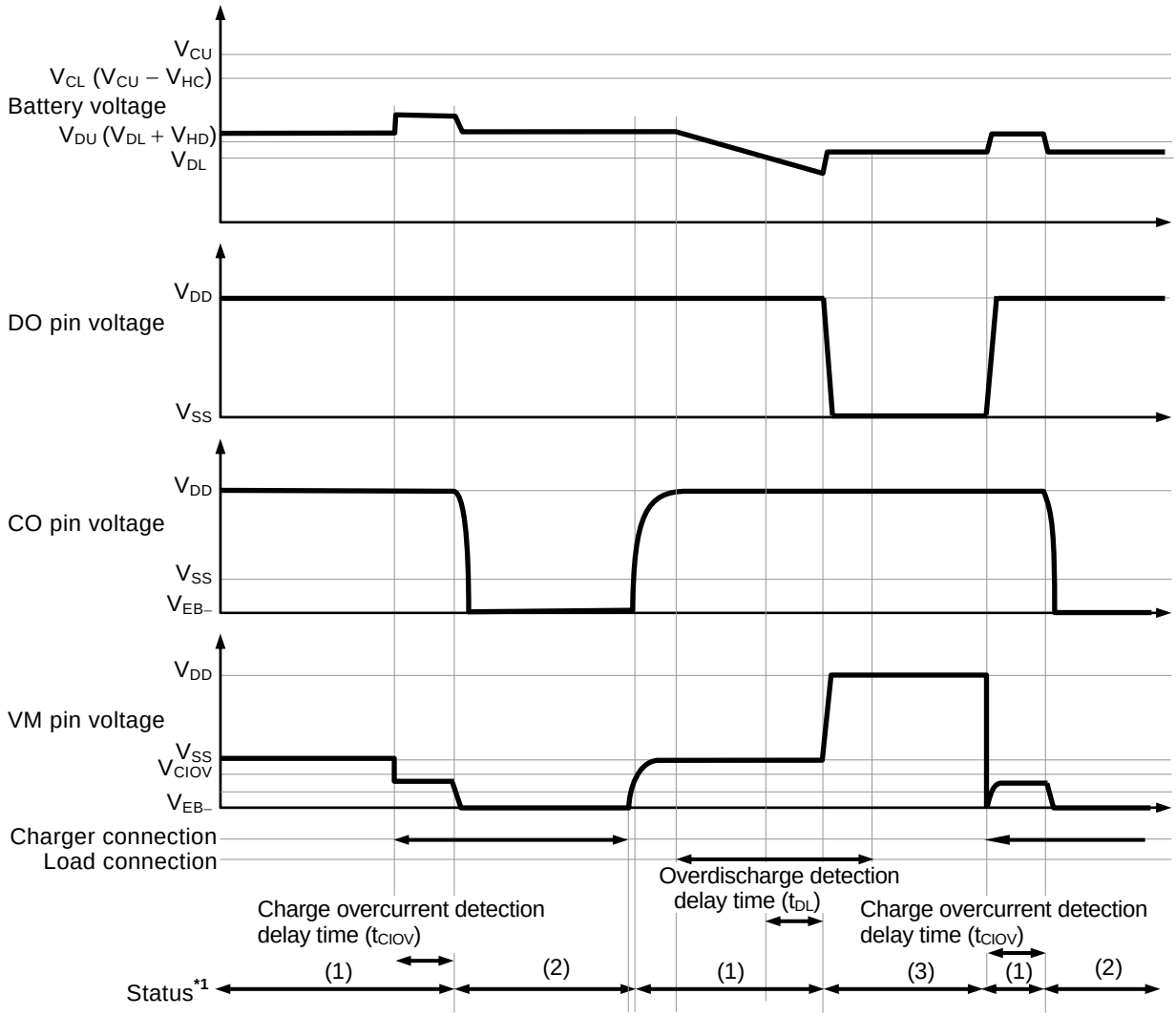


***1.** (1): Normal status
(2): Discharge overcurrent status

Remark The charger is assumed to charge with a constant current.

Figure 12

3. Charge overcurrent detection



***1.** (1): Normal status
(2): Charge overcurrent status
(3): Overdischarge status

Remark The charger is assumed to charge with a constant current.

Figure 13

■ Battery Protection IC Connection Example

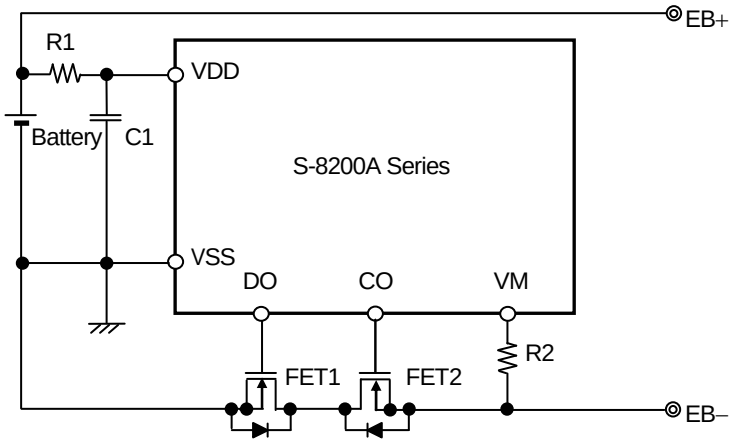


Figure 14

Table 11 Constants for External Components

Symbol	Part	Purpose	Typ.	Min.	Max.	Remark
FET1	N-channel MOS FET	Discharge control	–	–	–	Threshold voltage ≤ Overdischarge detection voltage[*1] Gate to source withstanding voltage ≥ Charger voltage[*2]
FET2	N-channel MOS FET	Charge control	–	–	–	Threshold voltage ≤ Overdischarge detection voltage[*1] Gate to source withstanding voltage ≥ Charger voltage[*2]
R1	Resistor	ESD protection, For power fluctuation	330 Ω	150 Ω	1 kΩ	Resistance should be as small as possible to avoid lowering the overcharge detection accuracy due to current consumption.[*3]
C1	Capacitor	For power fluctuation	0.1 μF	0.068 μF	1.0 μF	Connect a capacitor of 0.068 μF or higher between VDD pin and VSS pin.[*4]
R2	Resistor	Protection for reverse connection of a charger	2 kΩ	300 Ω	4 kΩ	Select as large a resistance as possible to prevent current when a charger is connected in reverse.[*5]

***1.** If the threshold voltage of an FET is low, the FET may not cut the charging current. If an FET with a threshold voltage equal to or higher than the overdischarge detection voltage is used, discharging may be stopped before overdischarge is detected.

***2.** If the withstanding voltage between the gate and source is lower than the charger voltage, the FET may be destroyed.

***3.** An accuracy of overcharge detection voltage is guaranteed by R1 = 330 Ω. Connecting resistors with other values worsen the accuracy. In case of connecting larger resistor to R1, the voltage between the VDD pin and VSS pin may exceed the absolute maximum rating because the current flows to the S-8200A Series from the charger due to reverse connection of charger. Connect a resistor of 150 Ω or more to R1 for ESD protection.

***4.** When connecting a resistor of 150 Ω or less to R1 or a capacitor of 0.068 μF or less to C1, the S-8200A Series may malfunction when power dissipation is largely fluctuated.

***5.** When a resistor more than 4 kΩ is connected to R2, the charge current may not be cut.

Caution 1. The above constants may be changed without notice.

2. It has not been confirmed whether the operation is normal or not in circuits other than the above example of connection. In addition, the example of connection shown above and the constant do not guarantee proper operation. Perform thorough evaluation using the actual application to set the constant.

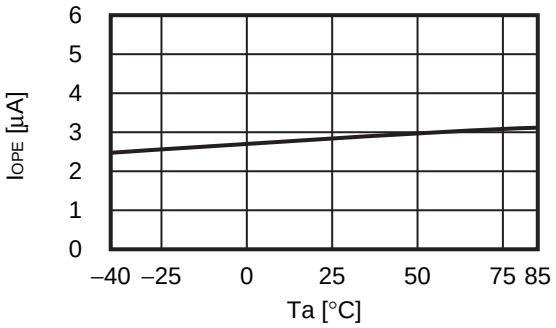
■ Precautions

- The application conditions for the input voltage, output voltage, and load current should not exceed the package power dissipation.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- SII claims no responsibility for any and all disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.

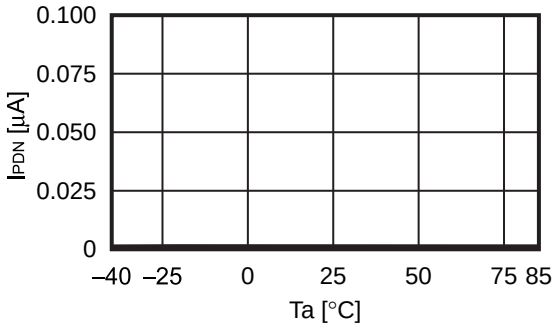
■ Characteristics (Typical Data)

1. Current consumption

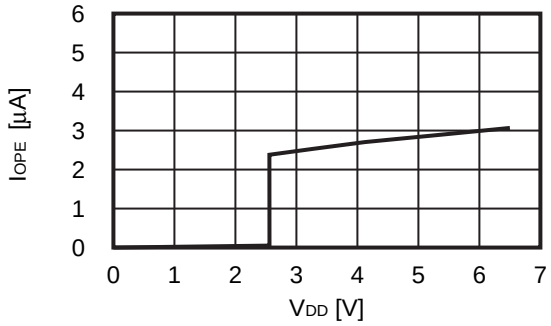
1. 1 I_{OPE} vs. Ta



1. 2 I_{PDN} vs. Ta

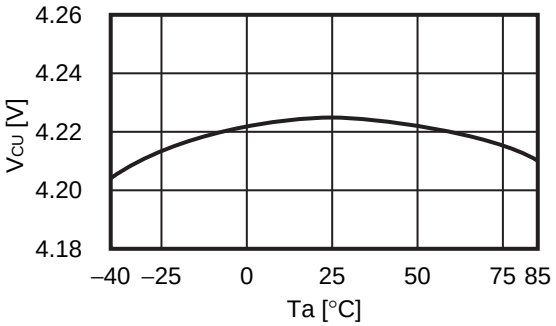


1. 3 I_{OPE} vs. V_{DD}

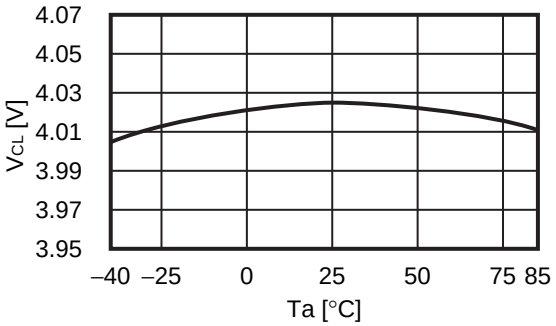


2. Overcharge detection / release voltage, overdischarge detection / release voltage, overcurrent detection voltage, charge overcurrent detection voltage, and delay time

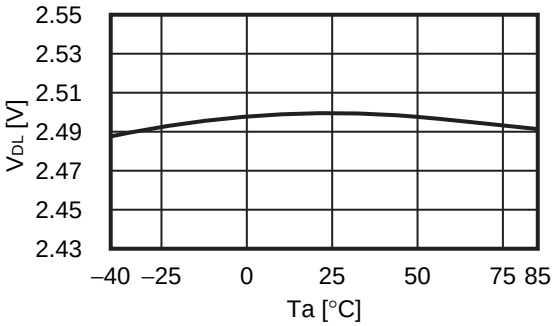
2. 1 V_{CU} vs. Ta



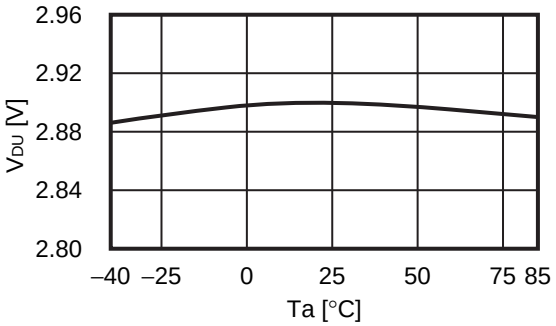
2. 2 V_{CL} vs. Ta



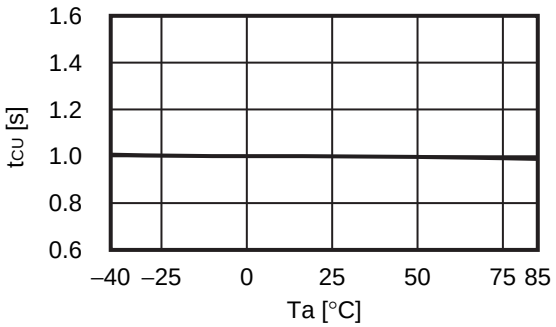
2. 3 V_{DL} vs. Ta



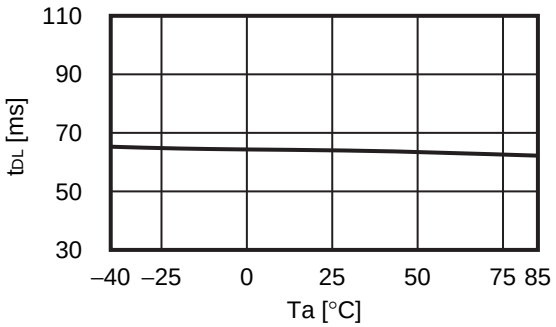
2. 4 V_{DU} vs. Ta



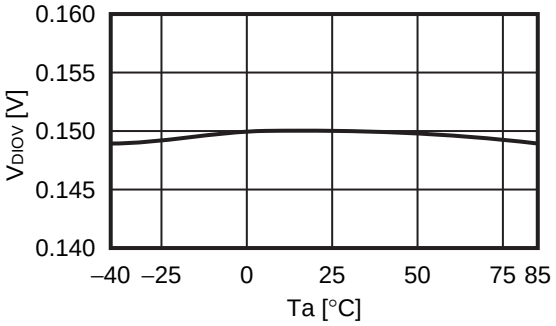
2. 5 t_{CU} vs. Ta



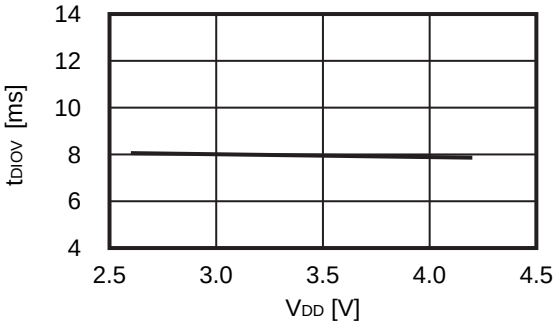
2. 6 t_{DL} vs. Ta



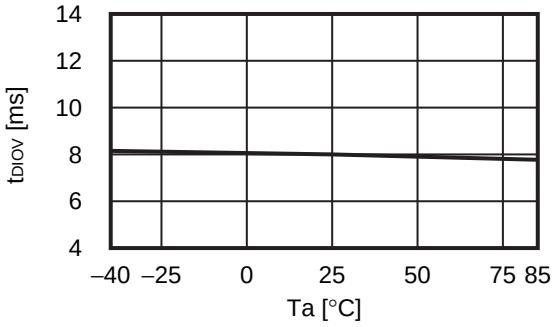
2. 7 V_{DIOV} vs. Ta



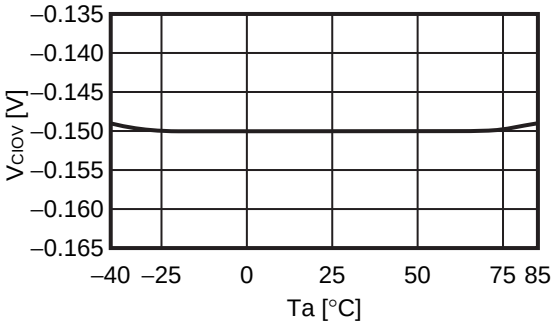
2. 8 t_{DIOV} vs. V_{DD}



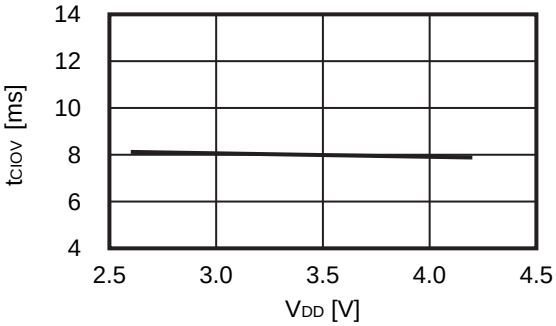
2. 9 t_{DIOV} vs. Ta



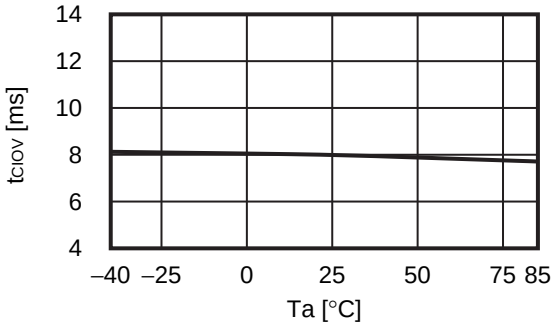
2. 10 V_{CIOV} vs. Ta



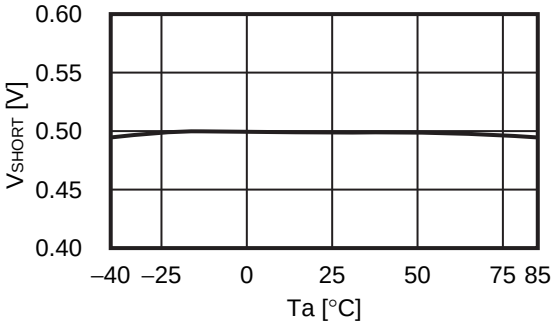
2. 11 t_{CIOV} vs. V_{DD}



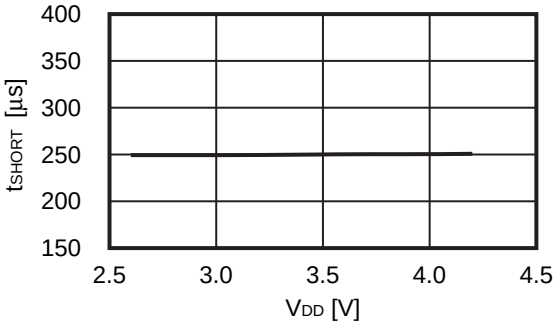
2. 12 t_{CIOV} vs. Ta



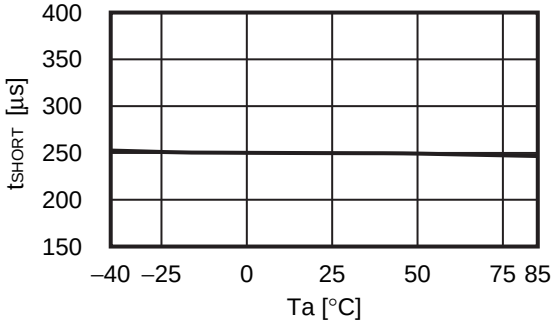
2. 13 V_{SHORT} vs. Ta



2. 14 t_{SHORT} vs. V_{DD}

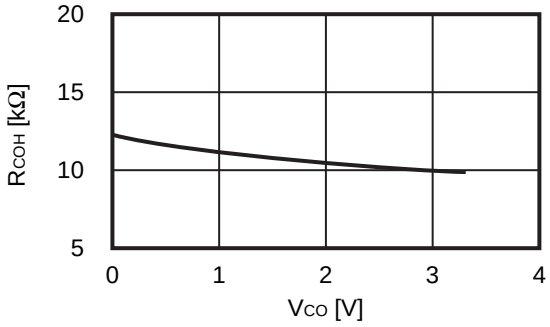


2. 15 t_{SHORT} vs. Ta

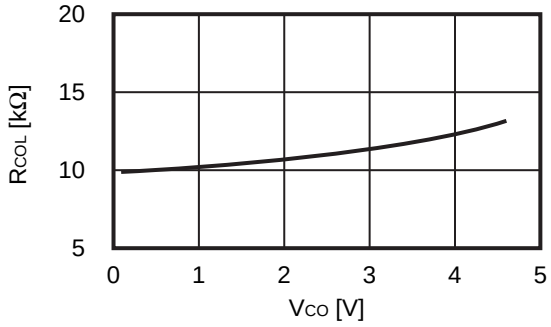


3. CO pin / DO pin

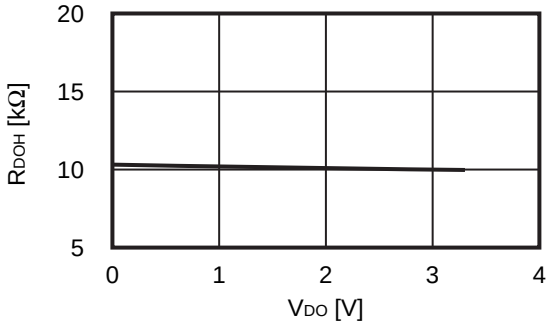
3. 1 R_{COH} vs. V_{CO}



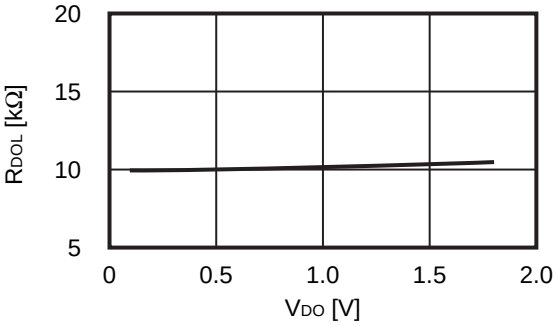
3. 2 R_{COL} vs. V_{CO}



3. 3 R_{DOH} vs. V_{DO}



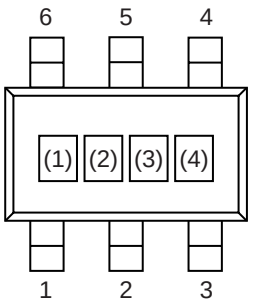
3. 4 R_{DOL} vs. V_{DO}



■ Marking Specifications

1. SOT-23-6

Top view



(1) to (3): Product code (refer to **Product name vs. Product code**)
(4): Lot number

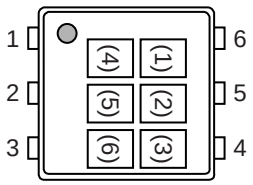
Product name vs. Product code

Product Name	Product Code		
	(1)	(2)	(3)
S-8200AAC-M6T1U	V	3	C
S-8200AAH-M6T1U	V	3	H
S-8200AAY-M6T1U	V	3	Y
S-8200ABE-M6T1U	V	4	E

Remark Please contact our sales office for the products other than those specified above.

2. SNT-6A

Top view

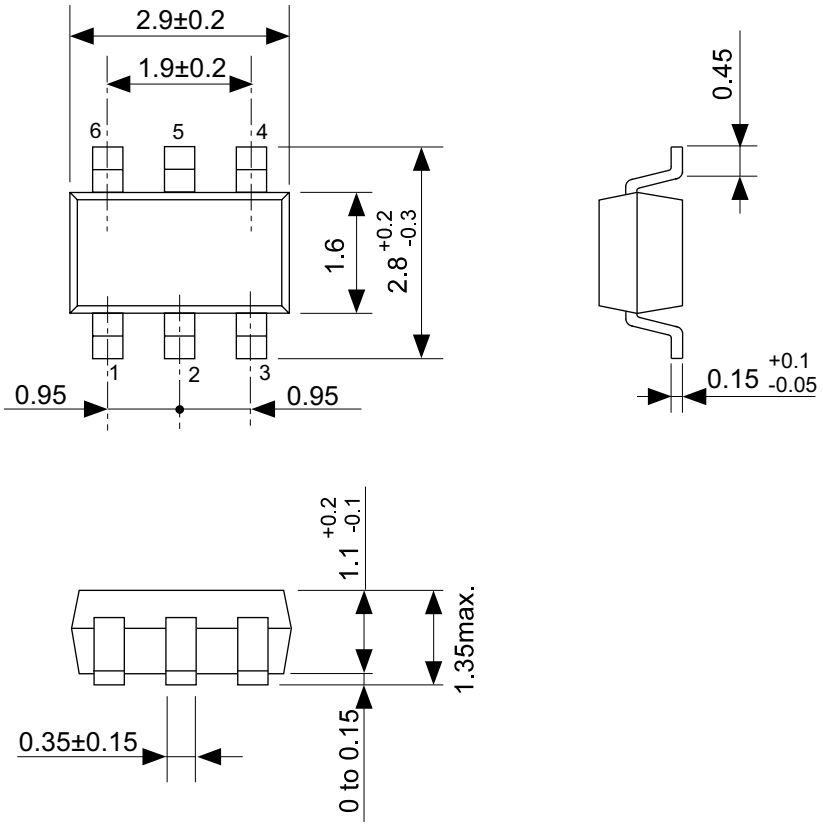


(1) to (3): Product code (refer to **Product name vs. Product code**)
(4) to (6): Lot number

Product name vs. Product code

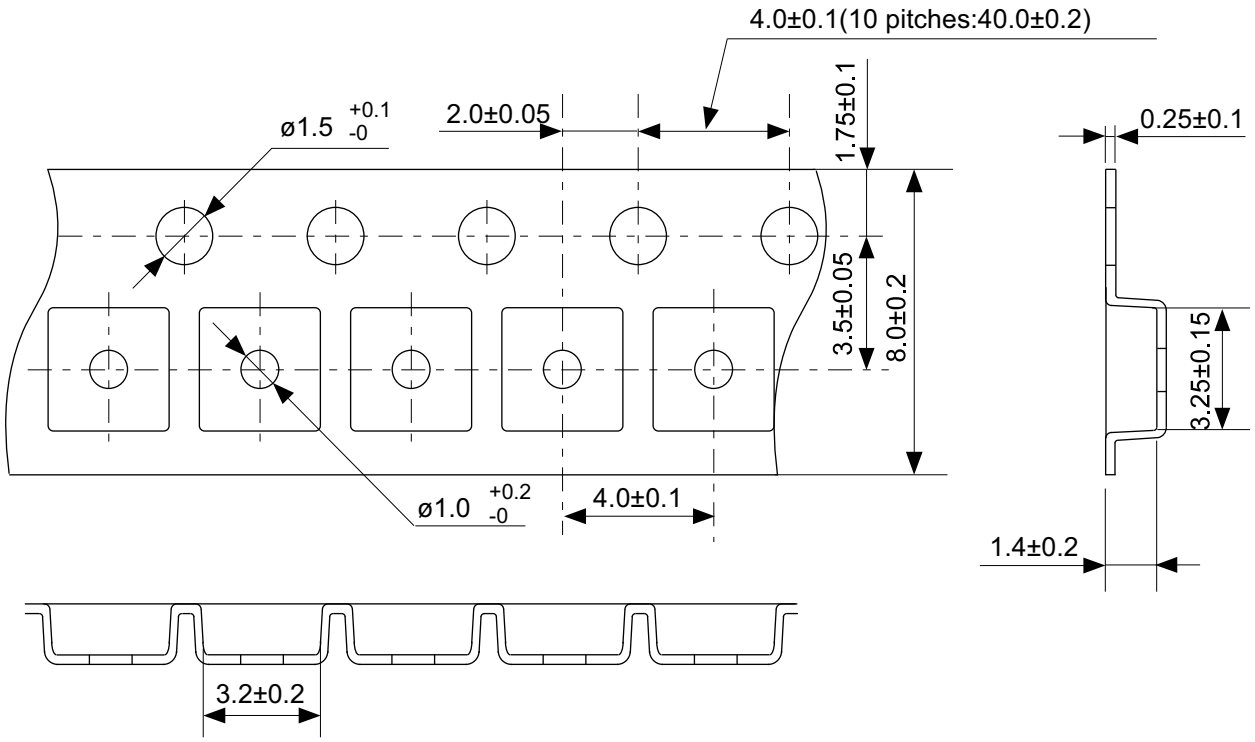
Product Name	Product Code		
	(1)	(2)	(3)
S-8200AAA-I6T1U	V	3	A
S-8200AAB-I6T1U	V	3	B
S-8200AAC-I6T1U	V	3	C
S-8200AAD-I6T1U	V	3	D
S-8200AAF-I6T1U	V	3	F
S-8200AAG-I6T1U	V	3	G
S-8200AAH-I6T1U	V	3	H
S-8200ABA-I6T1U	V	4	A

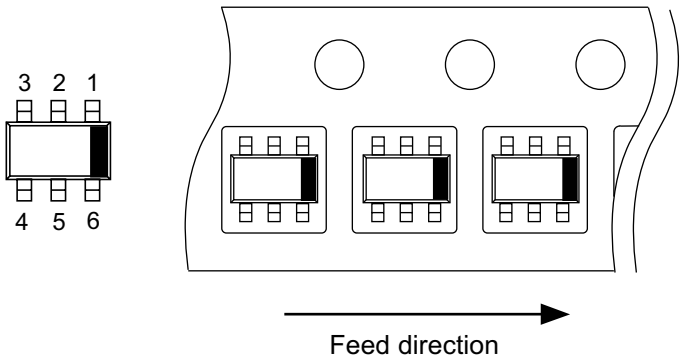
Remark Please contact our sales office for the products other than those specified above.



No. MP006-A-P-SD-2.0

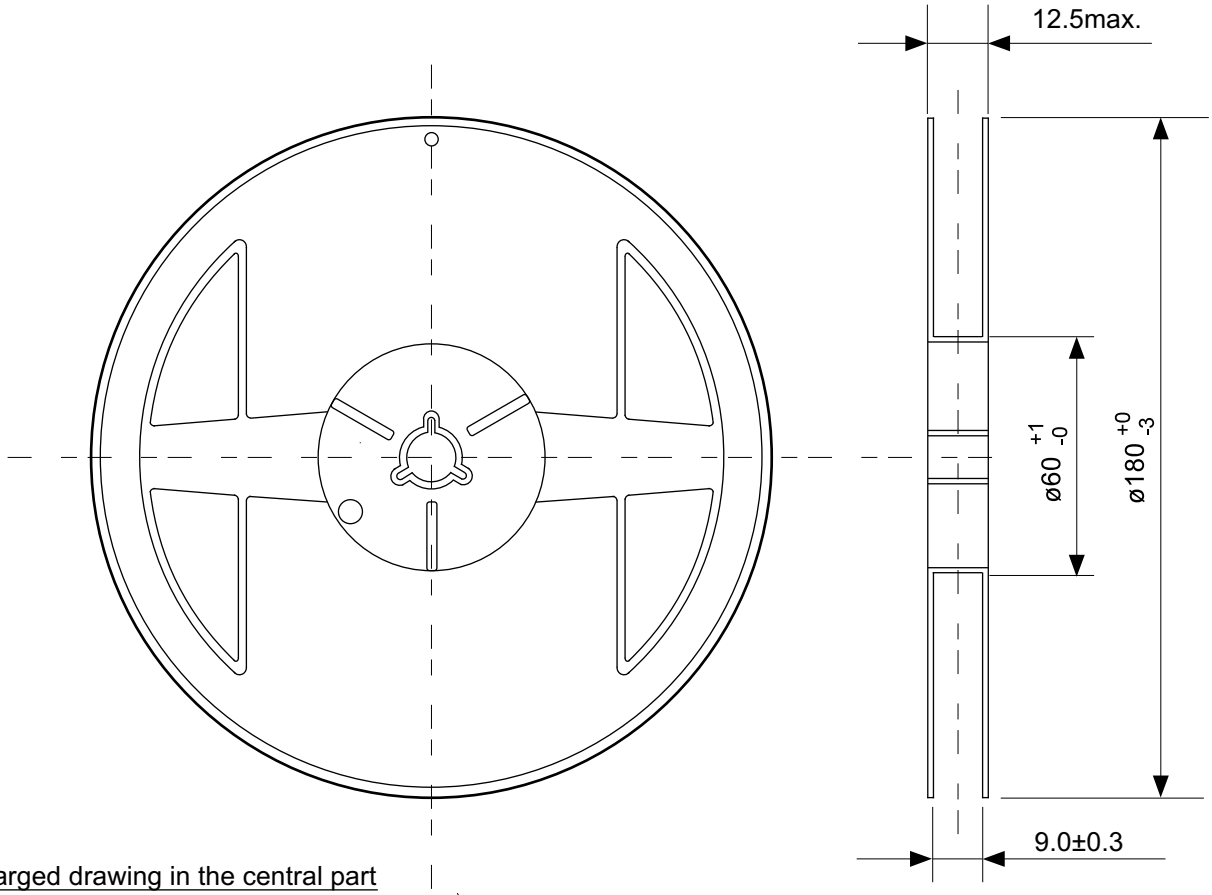
TITLE	SOT236-A-PKG Dimensions
No.	MP006-A-P-SD-2.0
SCALE	
UNIT	mm
Seiko Instruments Inc.	



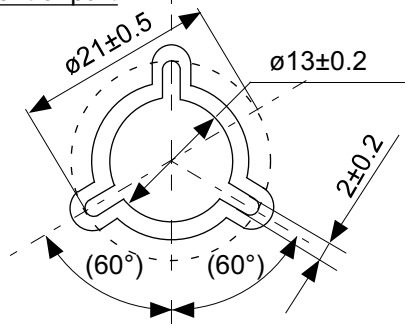


No. MP006-A-C-SD-3.1

TITLE	SOT236-A-Carrier Tape
No.	MP006-A-C-SD-3.1
SCALE	
UNIT	mm
Seiko Instruments Inc.	

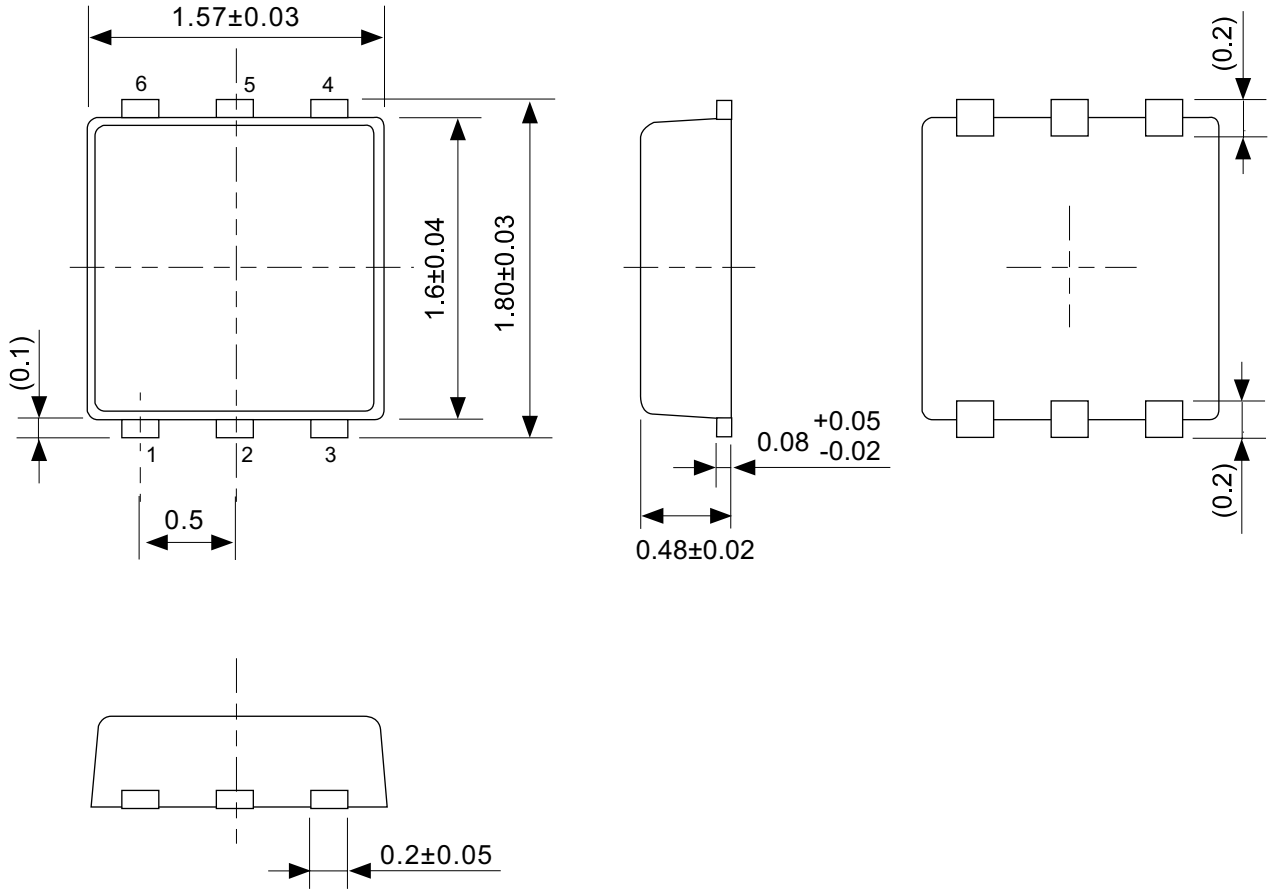


Enlarged drawing in the central part



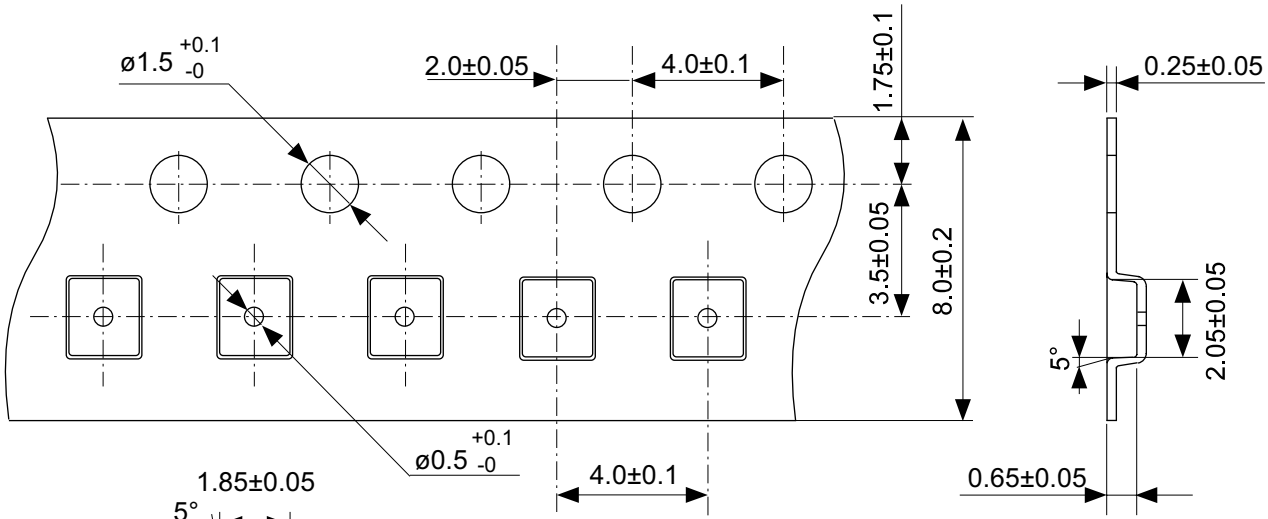
No. MP006-A-R-SD-2.1

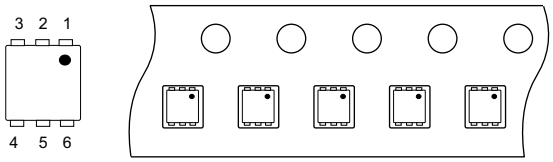
TITLE	SOT236-A-Reel		
No.	MP006-A-R-SD-2.1		
SCALE		QTY	3,000
UNIT	mm		
Seiko Instruments Inc.			



No. PG006-A-P-SD-2.0

TITLE	SNT-6A-A-PKG Dimensions
No.	PG006-A-P-SD-2.0
SCALE	
UNIT	mm
Seiko Instruments Inc.	

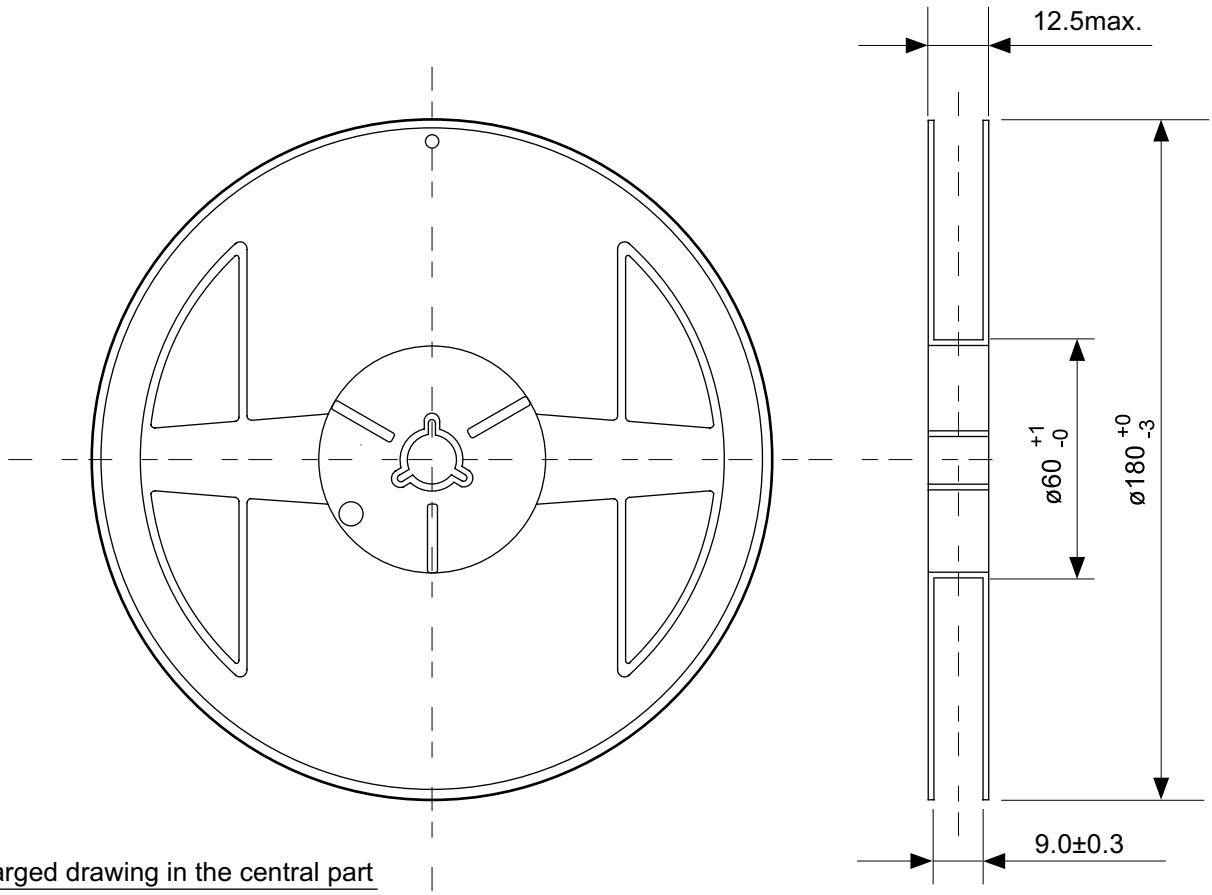




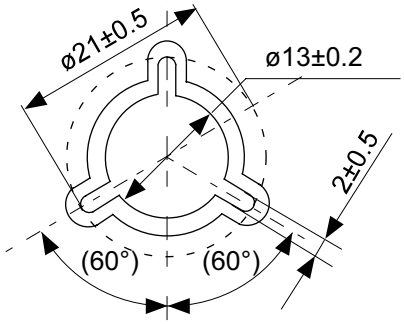
Feed direction

No. PG006-A-C-SD-1.0

TITLE	SNT-6A-A-Carrier Tape
No.	PG006-A-C-SD-1.0
SCALE	
UNIT	mm
Seiko Instruments Inc.	

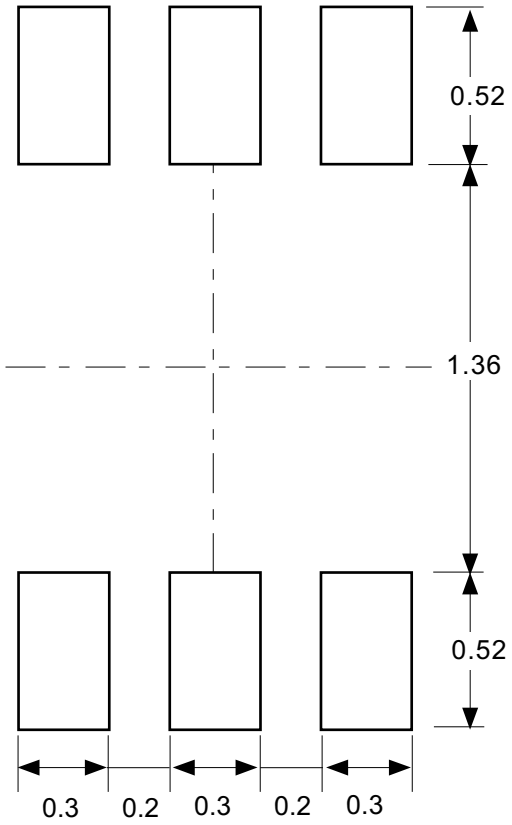


Enlarged drawing in the central part



No. PG006-A-R-SD-1.0

TITLE	SNT-6A-A-Reel		
No.	PG006-A-R-SD-1.0		
SCALE		QTY.	5,000
UNIT	mm		
Seiko Instruments Inc.			



Caution Making the wire pattern under the package is possible. However, note that the package may be upraised due to the thickness made by the silk screen printing and of a solder resist on the pattern because this package does not have the standoff.

注意 パッケージ下への配線パターン形成は可能ですが、本パッケージはスタンドオフが無いので、パターン上のレジスト厚み、シルク印刷の厚みによってパッケージが持ち上がることがありますのでご配慮ください。

No. PG006-A-L-SD-3.0

TITLE	SNT-6A-A-Land Recommendation
No.	PG006-A-L-SD-3.0
SCALE	
UNIT	mm
Seiko Instruments Inc.	

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